



Material Composition Declaration

EPC29215_55

Company Name	Efficient Power Conversion (EPC)	Issue Date:	4/24/2024
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	10.0 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	8.4915	84.8473	88.4316	848473
	Silicon oxide	7631-86-9	0.0573	0.5722		5722
	Silicon nitride	12033-89-5	0.0189	0.1888		1888
	Gallium nitride	25617-97-4	0.0672	0.6717		6717
	Aluminum	7429-90-5	0.0982	0.9810		9810
	Aluminum nitride	24304-00-5	0.0138	0.1377		1377
	Titanium	7440-32-6	0.0020	0.0196		196
	Titanium nitride	25583-20-4	0.0123	0.1231		1231
	Copper	7440-50-8	0.0016	0.0164		164
	Tungsten	7440-33-7	0.0069	0.0690		690
	Polyimide		0.0806	0.8050		8050
Under Bump Metal	Titanium	7440-32-6	0.0016	0.0156	0.0774	156
	Copper	7440-50-8	0.0062	0.0619		619
Solder Bump	Copper	7440-50-8	0.0774	0.7734	11.4909	7734
	Nickel	7440-02-0	0.0462	0.4614		4614
	Lead	7439-92-1	0.9751	9.7434		97434
	Tin	7440-31-5	0.0513	0.5128		5128
Sum in total:			10.0080	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.